



Characteristics of InP Particles Detectors Structures

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Outline

- motivation
- initial substrate
- structures
- technology
- results
- conclusions



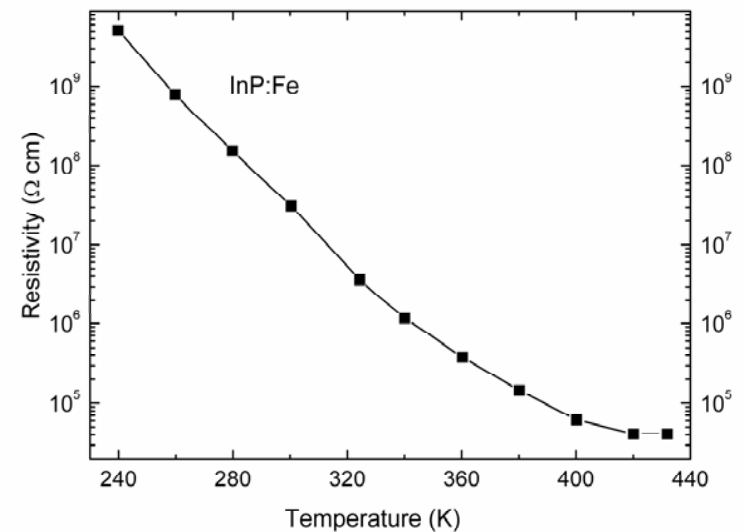
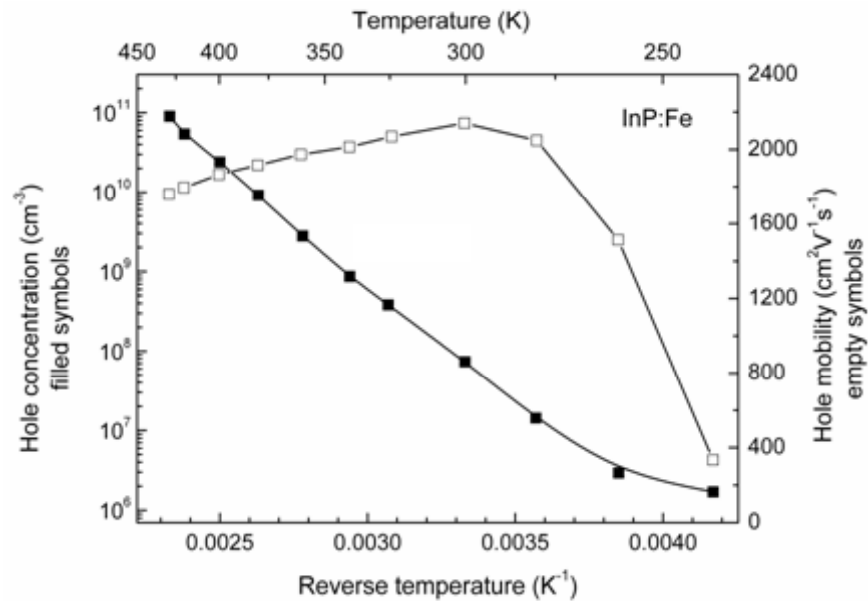
Motivation

Physical parameters of most used semiconductors at 300 K

| Material | Atomic number | Density g/cm ³ | Band-gap eV | Dielectric constant | Ionisation energy, eV | Resistivity Ohm.cm | Mobility cm ² /V.s | | $\mu\tau$ product cm ² /V | |
|------------|---------------|---------------------------|-------------|---------------------|-----------------------|--------------------|-------------------------------|------------|----------------------------------------|---------------------------------------------|
| | | | | | | | e | h | e | h |
| Si | 14 | 2.33 | 1.12 | 11.7 | 3.62 | $\approx 10^4$ | 1400 | 480 | >1 | ≈ 1 |
| Ge | 32 | 5.33 | 0.67 | 16 | 2.96 | 50 | 3900 | 1900 | >1 | >1 |
| CdTe | 48,52 | 6.2 | 1.44 | 11 | 4.43 | 10^9 | 1100 | 100 | 3.3×10^{-3} | 2×10^{-4} |
| GaAs | 31,33 | 5.32 | 1.43 | 12.8 | 4.2 | 10^7 | 8000 | 400 | 8×10^{-5} | 4×10^{-6} |
| InP | 49,15 | 4.78 | 1.35 | 12.5 | 4.2 | 10^7 | 4600 | 150 | 4.8×10^{-6} | $< 1.5 \times 10^{-5}$ |

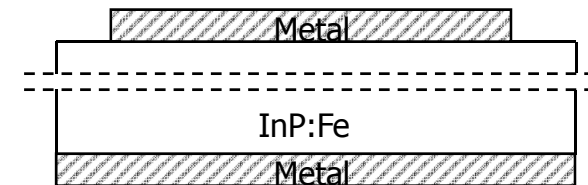
Initial substrate InP

- SI InP : Fe , (100) n – type,
- binding energy 0,64 eV

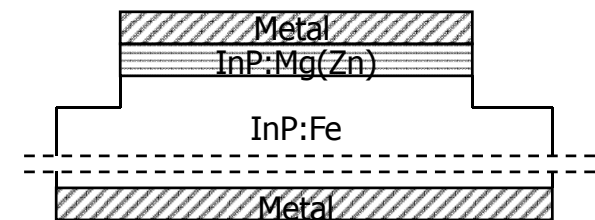


InP detector structures

- Schottky junction

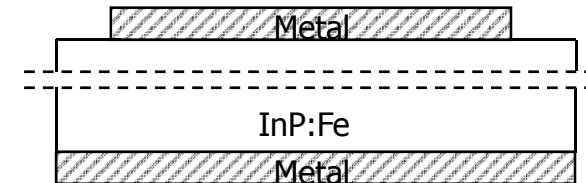


- Epilayer junction



Technology of Schottky barrier

- Contact metal
(6 nm Ni, 60 nm AuGe,
30 nm Ni, 200 nm Au)
annealing in nitrogen,
2 min. at 400°C
- Schottky junction
 $\phi = 2 \text{ mm}$
(same material
not annealed)



Epilayer junction technology

Liquid phase epitaxy technique
- epilayer of thickness 1 μm

Dopant Mg: $2,1 \cdot 10^{17} \text{cm}^{-3}$

MESA etch in $\text{HBr}:\text{K}_2\text{Cr}_2:\text{H}_2\text{O}$

Metal:

On P side:

AuBe (25 nm)

Cr (50 nm)

Au (200 nm)

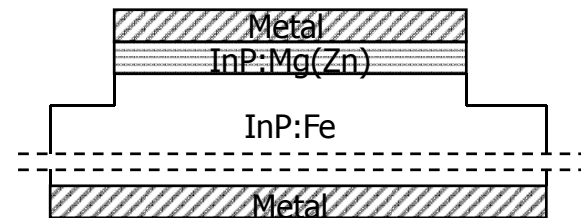
On N side:

Ni (6 nm)

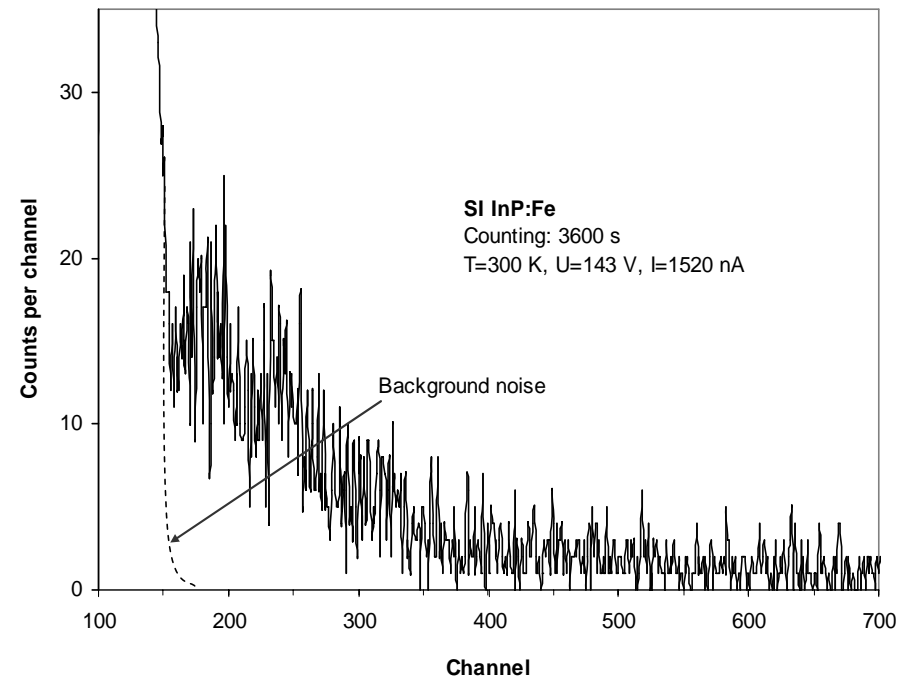
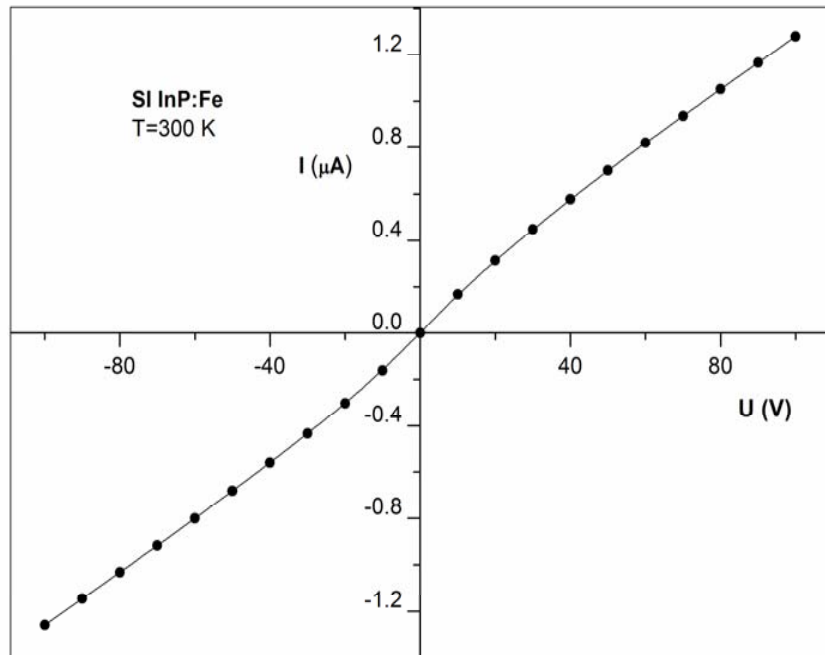
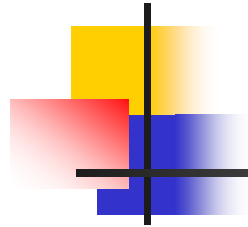
AuGe (60 nm)

Ni (30 nm)

Au(200 nm)



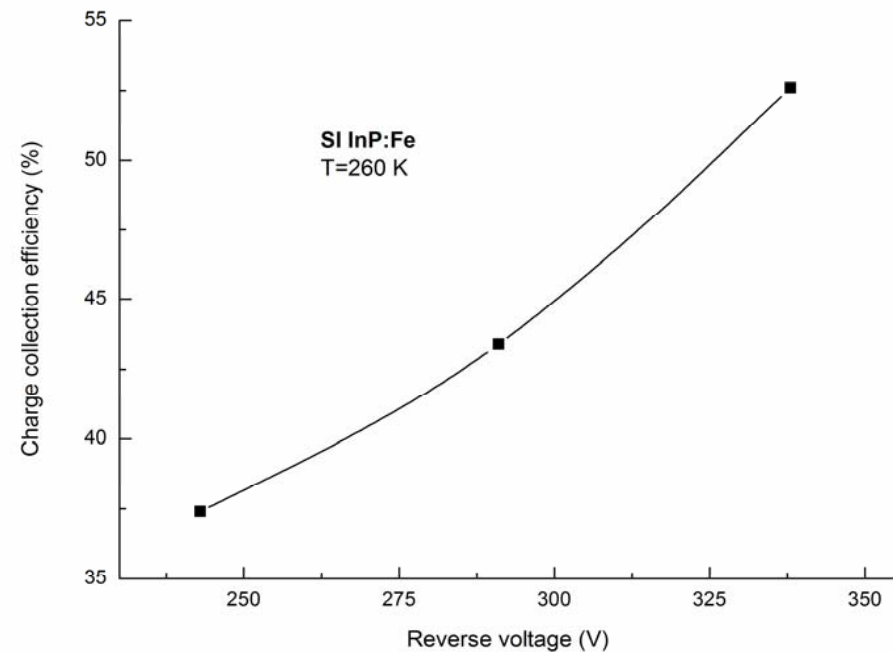
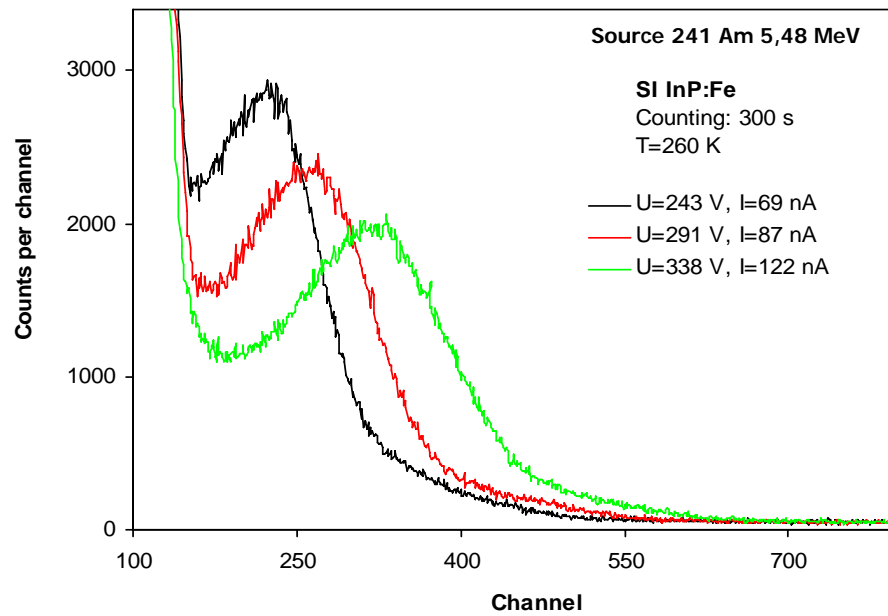
Detector on InP:Fe substrate Schottky (1)



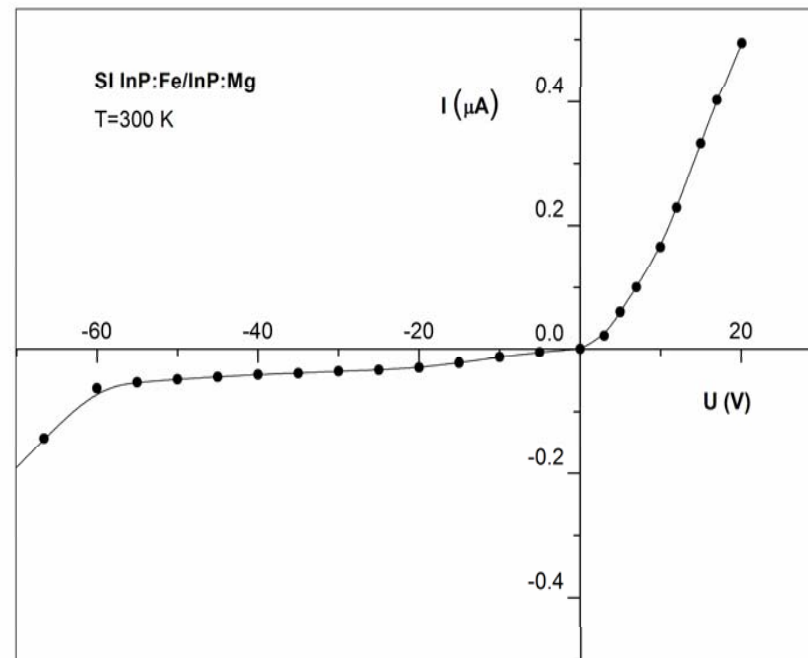
11.-13th Nov.2007

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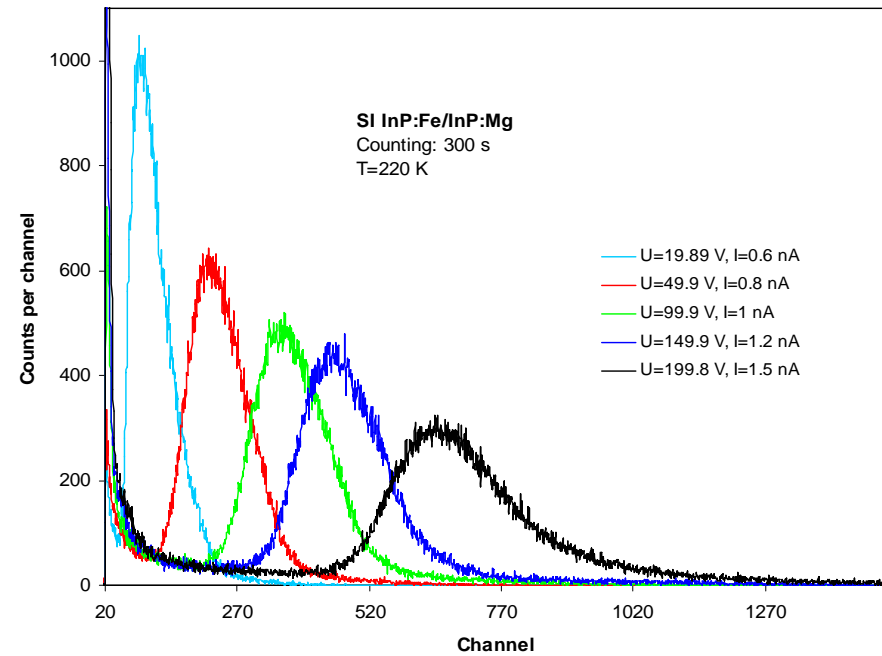
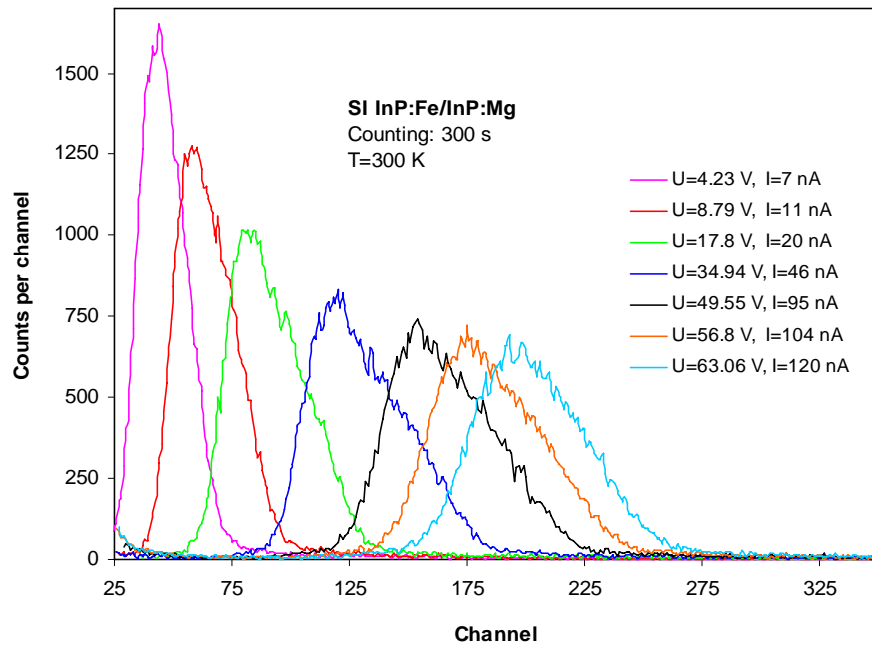
Detector on InP:Fe substrate Schottky (2)



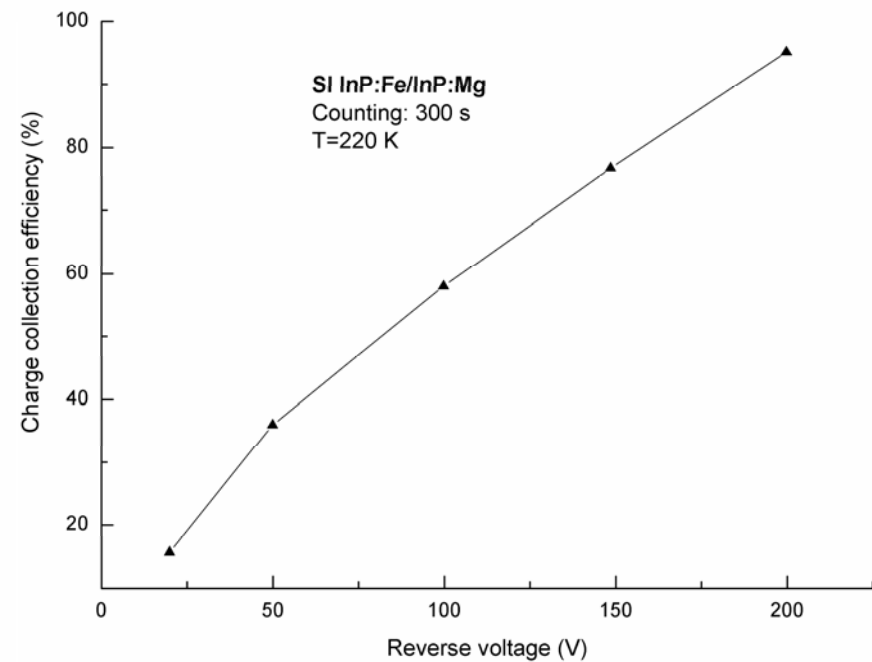
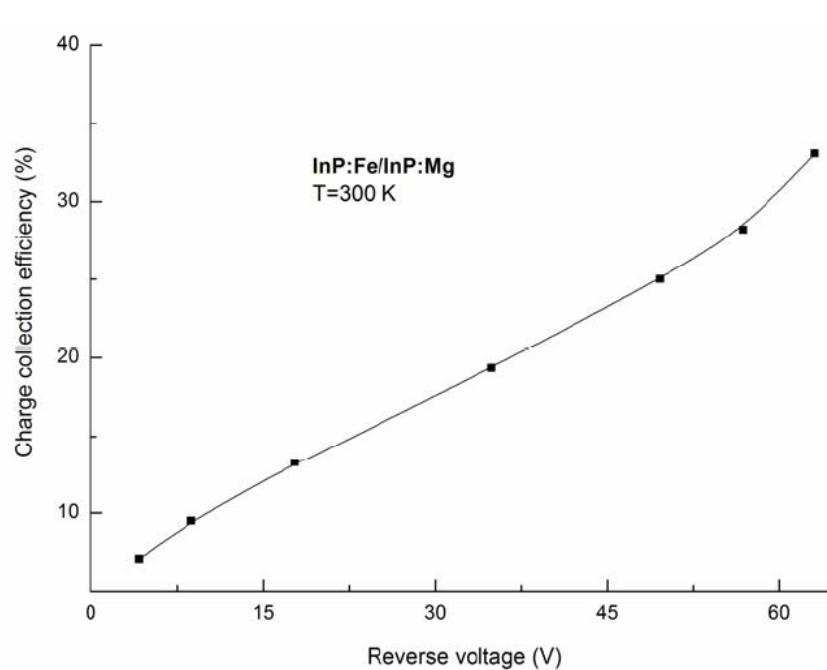
Detector on InP:Fe substrate epilayer junction (1) Mg, T=300 K



Detector on InP:Fe substrate epilayer junction (2) Mg



Detector on InP:Fe substrate epilayer junction (3) Mg, CCE





Conclusion

- technology of InP:Fe with epilayer InP:Mg was managed
- detectors produced with InP:Mg epilayer have better characteristics than InP:Fe Schottky diodes at 220 K
- InP:Mg epilayer structure operates at RT



Near Future Investigation

- standardization of horizontal structure and technology
- application of Be dopant
- study of radiation hardness